



# 100% Material Declaration Data Sheet PQG44

PK208 (v1.0) October 5, 2006

Material Declaration Data Sheet

**Average Weight: 0.50052 g**

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
<b>Silicon Die</b>					<b>0.01411</b>	<b>2.81%</b>
	Silicon	7440-21-3	100.00		0.01411	
<b>Die Attach Material</b>					<b>0.00352</b>	<b>0.70%</b>
	Silver	7440-22-4	70.00		0.002467	
	Epoxy (EP)	Trade Secret	20.00		0.000705	
	Anhydride	Trade Secret	10.00		0.000352	
<b>Mold Compound</b>					<b>0.34915</b>	<b>69.67%</b>
	Epoxy Resin (EP)	Trade Secret	15.00		0.052373	
	Silica	60676-86-0	85.00		0.296778	
<b>Leadframe</b>					<b>0.12312</b>	<b>24.57%</b>
	Copper	7440-50-8	98.20		0.118444	
	Nickel	7440-02-0	3.00		0.003694	
	Silicon	7440-21-3	0.65		0.00800	
	Magnesium	7440-95-4	0.15		0.000185	
<b>Leadframe Plating</b>					<b>0.001440</b>	<b>0.29%</b>
	Silver	7440-22-4	100.00		0.001440	
<b>Bond Wire</b>					<b>0.00101</b>	<b>0.20%</b>
	Gold	7440-57-5	100.00		0.00101	
<b>Ext. Plating</b>					<b>0.00817</b>	<b>1.76%</b>
	Tin	7440-31-5	100.00		0.00817	

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## Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
10/5/06	1.0	Initial release.